MSKSEMI















ESD

TVS

TSS

MOV

GDT

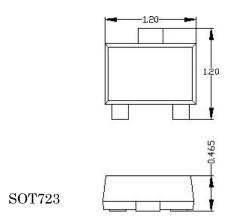
PLED

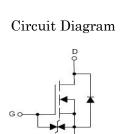
Broduct data speet





High Density Cell Design for Low RDS(ON) Voltage Controlled Small Signal Switch Small Outline Surface Mount Package RoHS compliant / Green EMC





ELECTRICAL CHARACTERISTICS @ 25° C Unless Otherwise Specified

Symbo1	Parameter	Test Conditions	Min	Тур	Max	Units
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V_{GS} =0V, I_D =250 μ A	60			V
$V_{GS(th)}$	Gate-Threshold Voltage	V _{DS} =VGS, I _D =250μA	1.0	1.4	2.5	V
I _{DSS}	Zero Gate Voltage Drain Current	V_{DS} =48V, V_{GS} =0V			1.0	uА
I _{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			±10	μA
		$V_{GS}=\pm 10V$, $V_{DS}=0V$			±200	nA
		$V_{GS}=\pm 5V$, $V_{DS}=0V$			±100	nA

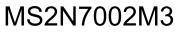


MAXIMUM RATINGS (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
$ m V_{DS}$	Drain-Source Voltage	60	V
$ m V_{GS}$	Gate-Source Voltage	±20	V
V _{EBO}	Emitter-Base Voltage	6	V
I_{D}	Drain Current-Continuous	0.34	A
P_{D}	Power Dissipation	0.15	W
Rө ја	Thermal Resistance From Junction To Ambient	833	°C/W
Tj	Junction Temperature	150	$^{\circ}$ C
Tstg	Storage Temperature	-55~+150	$^{\circ}$

R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =10V, I _D =500mA	1.3	4.0	_	
		V _{GS} =4.5V,I _D =200mA	1.4	4.5	Ω	
Qr	Recovered Charge	V_{GS} =0V, I_S =300mA, V_R =25V dl/dt=-100A/ μ s	30		nC	
Dynamic	Characteristics					
C _{iss}	Input Capacitance			40		
C_{oss}	Output Capacitance	V _{DS} =10V,V _{GS} =0V, f=1MHz		30	рF	
	Reverse Transfer			10		
C_{rss}	Capacitance					
Switchir	g Characteristics					
$t_{d(on)}$	Turn-on Delay Time	V_{DD} =25V, V_{GS} =10V, R_L =250 Ω ,		10		
$t_{d(off)}$	Turn-off Delay Time	R_{GS} =50K, R_{GEN} =25 Ω		15	nS	
t _{rr}	Reverse Recovery Time	V_{GS} =0V, I_{S} =300mA, V_{R} =25V,	30		1110	
		dl/dt=−100A/µs				
Source	-Drain Diode Characte	ristics				
V _{SD}	Diode Forward	V _{GS} =0V, I _S =200mA			.,	
	Voltage	V _{GS} -0V, I _S -200111A	0.97	1.5	V	



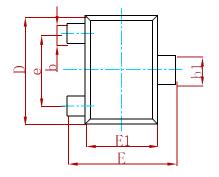


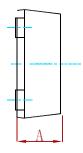


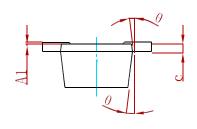




PACKAGE MECHANICAL DATA

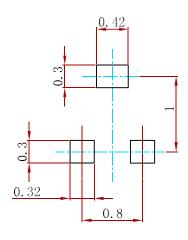






Compleal	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	0.430	0.500	0.017	0.020	
A1	0.000	0.050	0.000	0.002	
b	0.170	0.270	0.007	0.011	
b1	0.270	0.370	0.011	0.015	
С	0.080	0.150	0.003	0.006	
D	1.150	1.250	0.045	0.049	
E	1.150	1.250	0.045	0.049	
E1	0.750	0.850	0.030	0.033	
е	0.800TYP.		0.03	TYP.	
θ	7° REF.		7° REF.		

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MS2N7002M3	SOT-723	8000



Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with someprobability. It is possiblethat these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits anderror prevention circuitsfor safedesign, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from theauthorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. Whendesigning equipment, referto the "Delivery Specification" for the MSKSEMI Semiconductor productthat you intend to use.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by MSKSEMI manufacturer:

Other Similar products are found below:

614233C 648584F IRFD120 IRFF430 JANTX2N5237 2N7000 FCA20N60_F109 FDZ595PZ AOD464 2SK2267(Q) 2SK2545(Q,T)
405094E 423220D MIC4420CM-TR VN1206L 614234A 715780A SSM6J414TU,LF(T 751625C BSC884N03MS G BSF024N03LT3 G
PSMN4R2-30MLD TK31J60W5,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 EFC2J004NUZTDG FCAB21350L1 P85W28HP2F7071 DMN1053UCP4-7 NTE2384 NTE2969 NTE6400A DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7
SSM6P54TU,LF DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 STU5N65M6
C3M0021120D DMN13M9UCA6-7 BSS340NWH6327XTSA1 MCM3400A-TP DMTH10H4M6SPS-13 IRF40SC240ARMA1
IPS60R1K0PFD7SAKMA1